



100% Material Declaration Data Sheet SOG8

PK228 (v1.0) August 15, 2007

Material Declaration Data Sheet

Average Weight: 0.0811 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.003961	4.88%
	Silicon	7440-21-3	100.00		0.003961	
Die Attach Material					0.00124	1.53%
	Epoxy resin(EP)	19690-82-2	21.00		0.0002604	
	Silver	7440-22-4	70.00		0.000868	
	Misc.		9.0	(Metal oxide, amine, gamma butyrolactone)	0.0001116	
Mold Compound					0.041769	51.45%
	Resin	Trade secret	7.50		0.003133	
	SiO2 Filler	60676-86-0	86.00		0.035922	
	Carbon Black	1333-86-4	0.50		0.000209	
	Epoxy Cresol Novolac	Trade secret	2.00		0.000835	
	Phenol Resin	Trade secret	4.00		0.001671	
Leadframe					0.031983	39.36%
	Copper	7440-50-8	97.50		0.031184	
	Iron	7439-89-6	2.35		0.000752	
	Phosphorus	7723-14-0	0.03		0.000009	
	Zinc	7440-66-6	0.12		0.000038	
Leadframe Plating					0.000559	0.69%
	Silver	7440-22-4	100.00		0.000559	
Bond Wire					0.000223	0.27%
	Gold	7440-57-5	100.00		0.000223	
Ext. Plating					0.001364	1.82%
	Tin	7440-31-5	100.00		0.001364	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
8/15/07	1.0	Initial release.